

## Synchronous Buck PWM and Linear Controllers

### Features

- Provides Two Regulated Voltages
  - One Synchronous-Rectified Buck PWM Controller
  - One Linear Controller
- Low Reference Voltage for Further Applications
  - Both Controllers :  $0.8V \pm 2\%$  Over Temperature
- Both Controllers Drive N-Channel MOSFETs
  - PWM Controller Drives Dual N-Channel MOSFETs
  - Linear Controller Drives N-Channel MOSFET
- Built-in PWM Feedback Compensation
  - No Steady-State Error
  - Voltage-Mode PWM Control
  - Full 0~100% Duty Ratio
  - Fast Transient Response
- Adjustable Outputs by External Resistor Dividers
- Under-Voltage Monitoring on Both Controllers
- Small Converter Size
  - 600kHz Constant Switching Frequency
  - Built-In Soft-Start
  - Simple SO-8 Package
- Shutdown Control

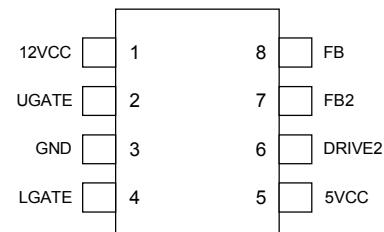
### Applications

- Motherboard
- Graphics Cards
- 12V, 5V and 3.3V Inputs DC-DC Converter

### General Description

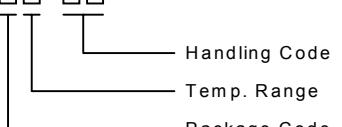
The APW7058 integrates one synchronous-rectified Buck PWM controller and one linear controller to provide two regulated voltages for graphics cards and other embedded processor applications. The PWM controller which drives dual N-channel MOSFETs uses fixed 600kHz frequency, voltage-mode PWM control and integrates power-on-reset(POR), built-in soft-start, output under-voltage monitoring and shutdown functions into a single chip. The linear controller which drives a N-channel MOSFET bypass transistor allows users to optimize the transient response by external components. The POR circuit with hysteresis monitors both 5VCC and 12VCC supply voltages to start up/shutdown the IC at power-on/off. An internal 0.8V temperature-compensated reference is designed to meet the low output voltage requirement for further applications. The built-in soft-start function sets the soft-start interval to prevent the output voltages from overshoot as well as limiting the input currents. The under-voltage protections monitor the voltages at FB and FB2 for short-circuit protection. The under-voltage protections cycle the soft-start function until 3 times of UVP events are happened. Pulling and holding the FB2 pin above 1.28V to disable the both controllers.

### Pin Description

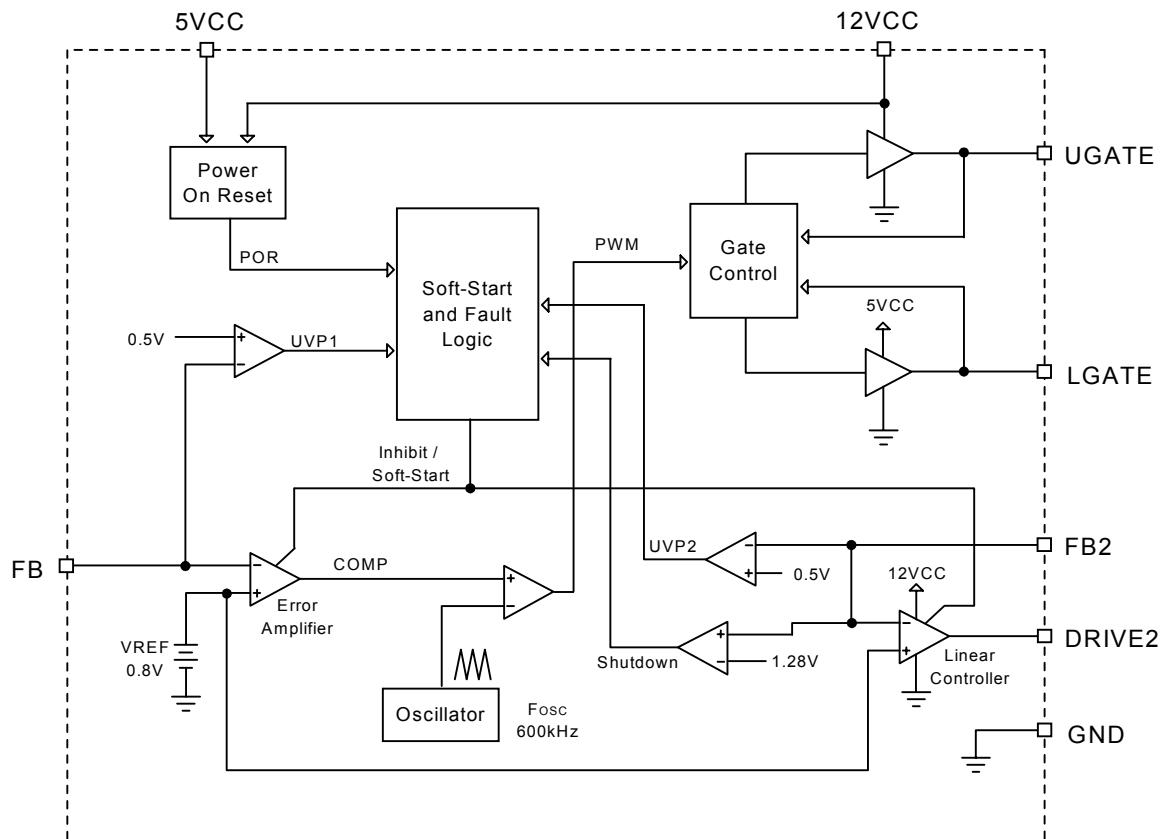


ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

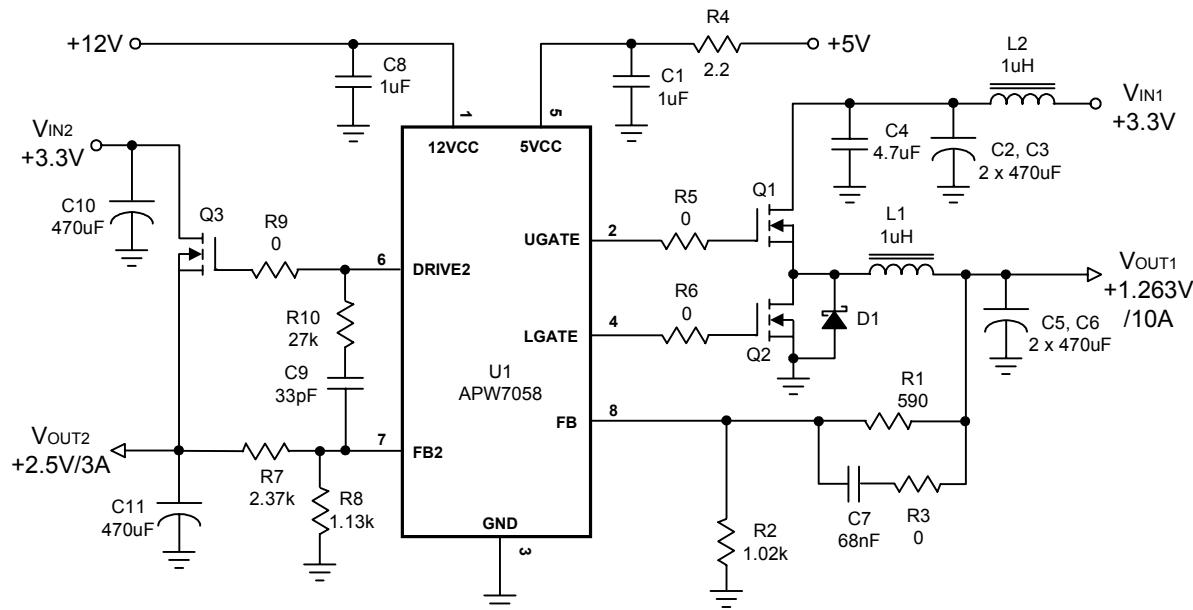
## Ordering and Marking Information

APW7058 □□-□□  Handling Code Temp. Range Package Code	Package Code K : SOP - 8 Operating Junction Temp. Range C : 0 to 70°C Handling Code TU : Tube TR : Tape & Reel
APW7058 K : <span style="border: 1px solid black; padding: 2px;">APW7058 XXXXX</span>	XXXXX - Date Code

## Block Diagram



## Typical Application



Q1, Q2 : APM2014N UC

D1 : 3A Schottky Diode

Q3 : APM2055N UC

C2, C3, C5, C6, C10, C11 : 470μF/6.3V, ESR=30mΩ

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
5V <sub>CC</sub>	5VCC Supply Voltage (5VCC to GND)	-0.3 ~ 7	V
12V <sub>CC</sub>	12VCC Supply Voltage (12VCC to GND)	-0.3 ~ 15	V
	UAGTE, DRIVE2 to GND	-0.3 ~ 12V <sub>CC</sub>	V
	LGATE, FB, FB2 to GND	-0.3 ~ 5V <sub>CC</sub>	V
	Maximum Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	-65 ~ 150	°C
T <sub>SDR</sub>	Maximum Soldering Temperature, 10 Seconds	300	°C
V <sub>ESD</sub>	Minimum ESD Rating (Human body model)	±2	KV

## Thermal Characteristics

Symbol	Parameter	Value	Unit
θ <sub>JA</sub>	Junction-to-Ambient Resistance in free air (SOP-8)	160	°C/W





## Functional Pin Description

### **12VCC (Pin 1)**

Connect this pin to 12V supply voltage. It provides bias voltage for the high-side MOSFET driver and the linear controller. The voltage at this pin is monitored for Power-On-Reset purposes.

### **UGATE (Pin 2)**

Connect this pin to the gate of the high-side MOSFET. This pin provides gate drive for the MOSFET.

### **GND (Pin 3)**

Signal and power ground for the IC. Putting vias to ground planet directly and close to GND pins minimizes noises.

### **LGATE (Pin 4)**

Connect this pin to the gate of the low-side MOSFET. This pin provides gate drive for the MOSFET.

### **5VCC (Pin 5)**

Connect this pin to a 5V supply voltage via a RC filter (2.2Ω and 1μF are recommended). This pin provides the bias for the control circuitry and the low-side MOSFET driver. The voltage at this pin is monitored for Power-On-Reset purposes.

### **DRIVE2 (Pin 6)**

Connect this pin to the gate of an external N-Channel MOSFET transistor. This pin provides the gate voltage for the linear regulator pass transistor. It also provides a means of compensating the linear controller for applications where the user needs to optimize the regulator transient response.

### **FB2 (Pin 7)**

Connect this pin to the output ( $V_{OUT2}$ ) of the linear regulator via a proper sized resistor divider. The voltage at this pin is regulated to 0.8V and the  $V_{OUT2}$  is determined using the following formula :

$$V_{OUT2}=0.8V \times \left(1 + \frac{R7}{R8}\right)$$

where R7 is the resistor connected from  $V_{OUT2}$  to FB2, and R8 is the resistor connected from FB2 to GND. This pin is also monitored for under-voltage events. Pulling and holding FB2 above 1.28V shuts down both regulators. Releasing FB2 initiates soft-start on both regulators.

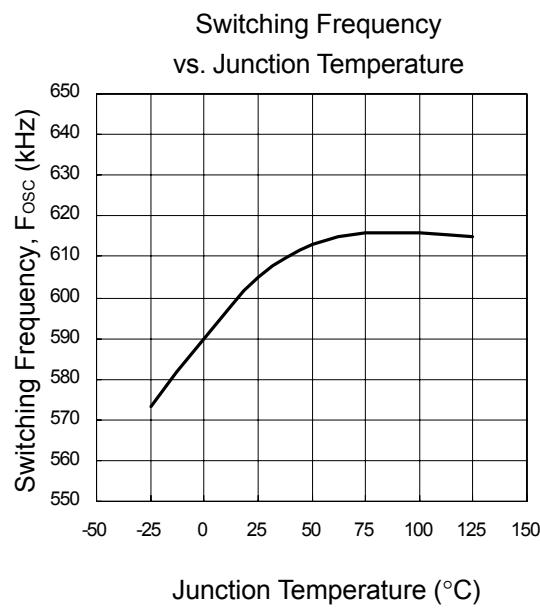
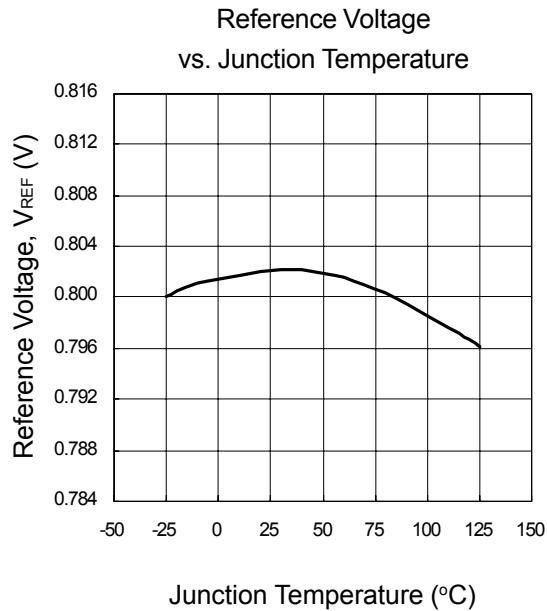
### **FB (Pin 8)**

This pin is the inverting input of the internal error amplifier. Connect this pin to the output ( $V_{OUT1}$ ) of the Buck converter via a proper sized resistor divider to provide feedback loop of the Buck converter. The  $V_{OUT1}$  is determined using the following formula :

$$V_{OUT1}=0.8V \times \left(1 + \frac{R1}{R2}\right)$$

where R1 is the resistor connected from  $V_{OUT1}$  to FB, and R2 is the resistor connected from FB to GND. This pin is also monitored for under-voltage events.

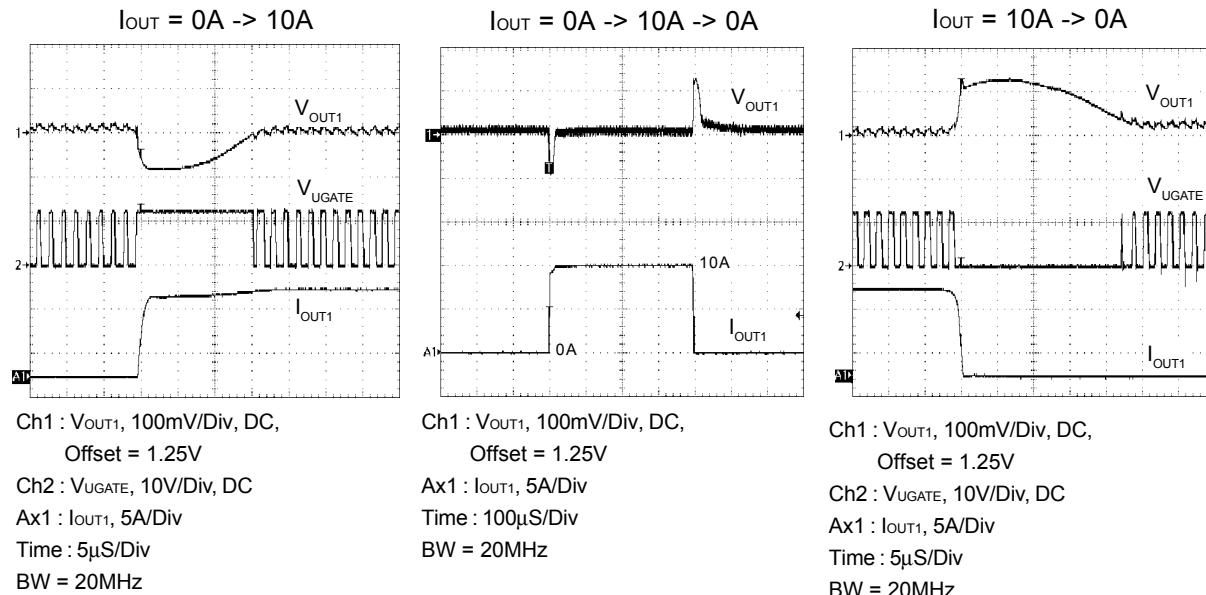
## Typical Characteristics



## Operating Waveforms (Refer to the typical application circuit)

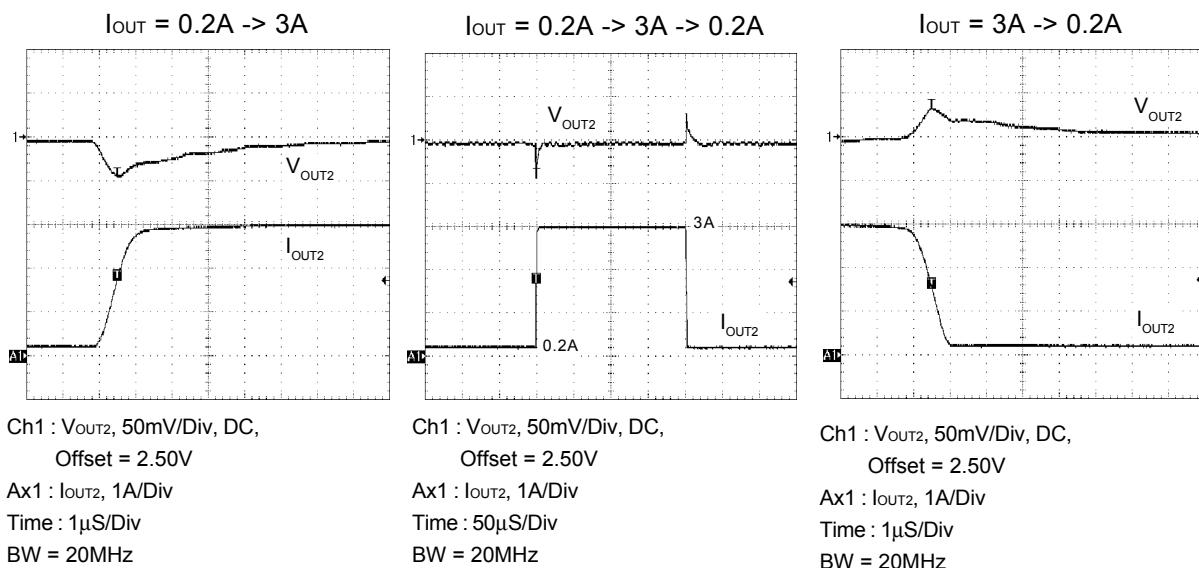
### 1. V<sub>OUT1</sub> Load Transient Response : I<sub>OUT</sub> = 0A → 10A → 0A

- I<sub>OUT1</sub> slew rate = ±10A/μS



### 2. V<sub>OUT2</sub> Load Transient Response : I<sub>OUT</sub> = 0.2A → 3A → 0.2A

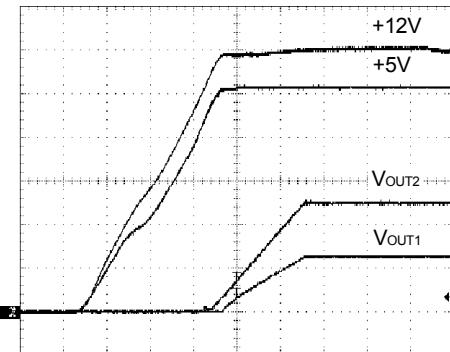
- I<sub>OUT2</sub> slew rate = ±3A/μS



## Operating Waveforms (Cont.)

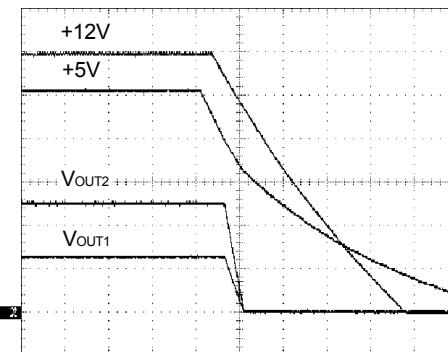
### 3. Powering ON / OFF

Soft-start at Powering ON



Ch1 : +5V, 1V/Div, DC  
Ch2 : +12V, 2V/Div, DC  
Ch3 : VOUT1, 1V/Div, DC  
Ch4 : VOUT2, 1V/Div, DC  
Time : 1mS/Div  
BW = 20MHz

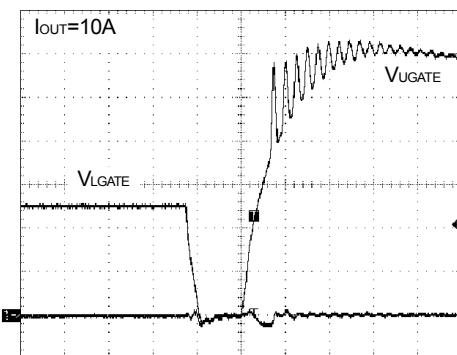
Powering OFF



Ch1 : +5V, 1V/Div, DC  
Ch2 : +12V, 2V/Div, DC  
Ch3 : VOUT1, 1V/Div, DC  
Ch4 : VOUT2, 1V/Div, DC  
Time : 5mS/Div  
BW = 20MHz

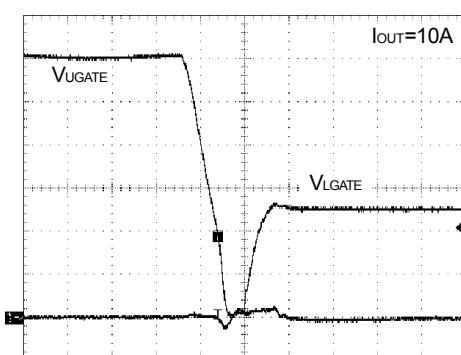
### 4. UGATE and LGATE

UGATE Rising



I<sub>OUT</sub>=10A  
Ch1 : VUGATE, 2V/Div, DC  
Ch2 : VLGATE, 2V/Div, DC  
Time : 50nS/Div  
BW = 500MHz

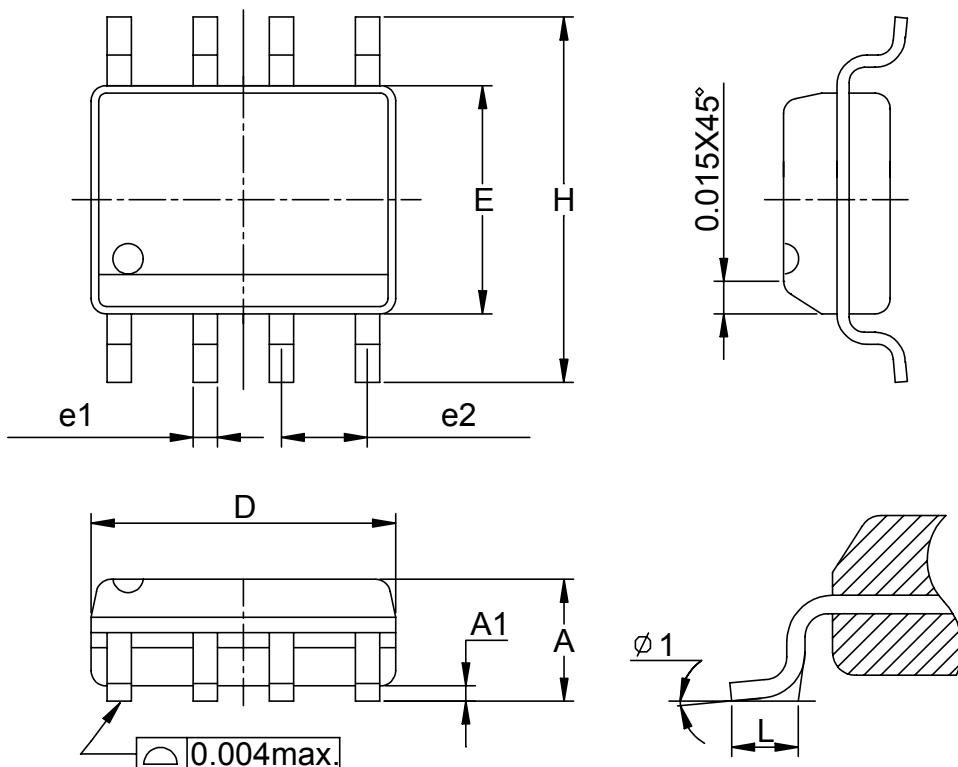
UGATE Falling



I<sub>OUT</sub>=10A  
Ch1 : VUGATE, 2V/Div, DC  
Ch2 : VLGATE, 2V/Div, DC  
Time : 50nS/Div  
BW = 500MHz

## Packaging Information

SOP-8 pin ( Reference JEDEC Registration MS-012)



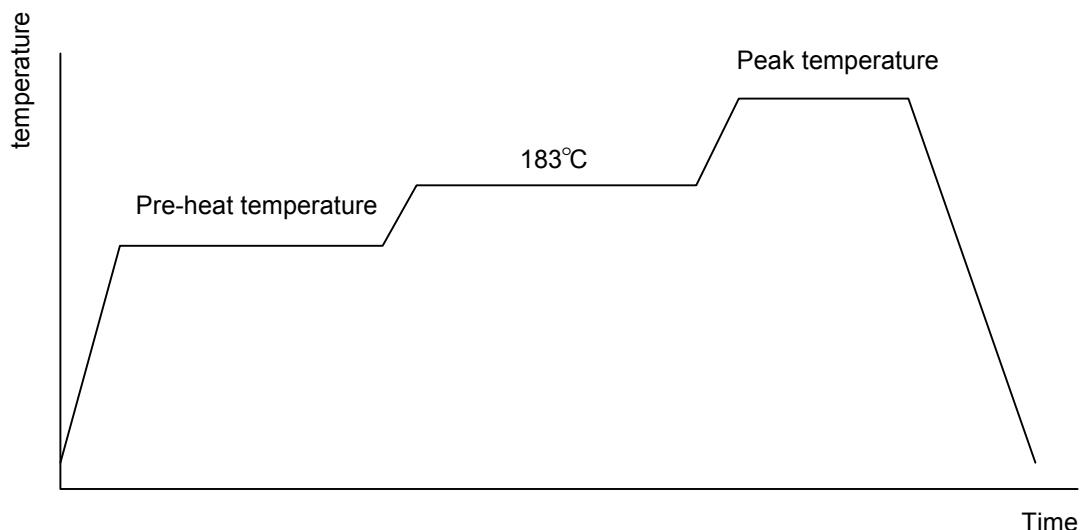
Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A <sub>1</sub>	0.10	0.25	0.004	0.010
D	4.80	5.00	0.189	0.197
E	3.80	4.00	0.150	0.157
H	5.80	6.20	0.228	0.244
L	0.40	1.27	0.016	0.050
$e_1$	0.33	0.51	0.013	0.020
$e_2$	1.27BSC		0.50BSC	
$\phi 1$	$8^\circ$		$8^\circ$	

## Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material : 90/10 or 63/37 SnPb)
Lead Solderability	Meets EIA Specification RSI86-91, ANSI/J-STD-002 Category 3.
Packaging	2500 devices per reel

### Reflow Condition (IR/Convection or VPR Reflow)

Reference JEDEC Standard J-STD-020A APRIL 1999



### Classification Reflow Profiles

	Convection or IR/ Convection	VPR
Average ramp-up rate(183 °C to Peak)	3 °C/second max.	10 °C /second max.
Preheat temperature 125 ± 25 °C)	120 seconds max.	
Temperature maintained above 183 °C	60 ~ 150 seconds	
Time within 5 °C of actual peak temperature	10 ~ 20 seconds	60 seconds
Peak temperature range	220 +5/-0 °C or 235 +5/-0 °C	215~ 219 °C or 235 +5/-0 °C
Ramp-down rate	6 °C /second max.	10 °C /second max.
Time 25 °C to peak temperature	6 minutes max.	

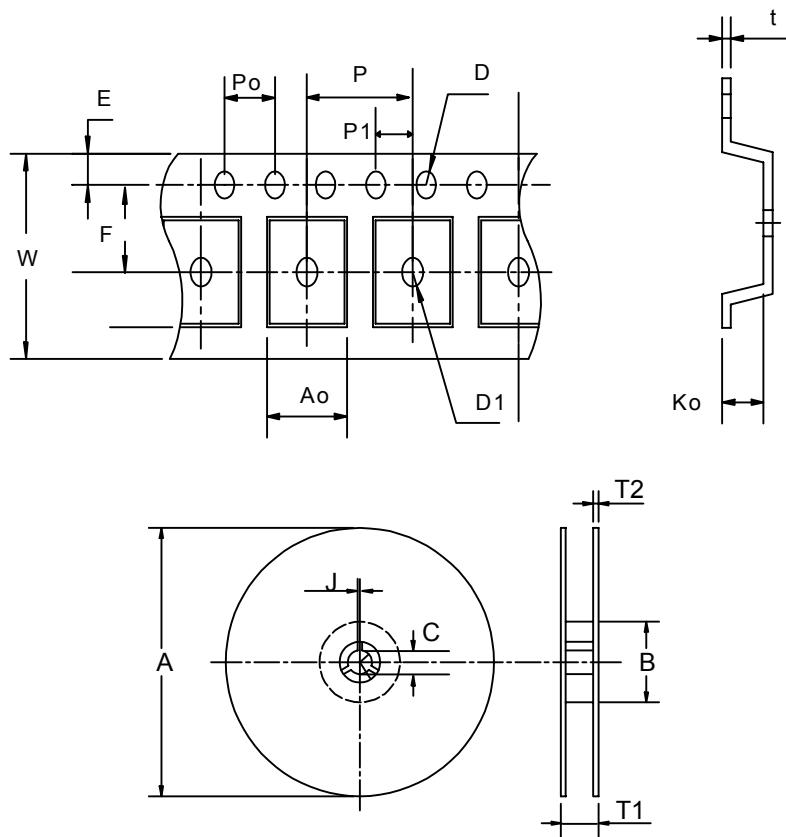
### Package Reflow Conditions

pkg. thickness ≥ 2.5mm and all bags	pkg. thickness < 2.5mm and pkg. volume ≥ 350 mm	pkg. thickness < 2.5mm and pkg. volume <
Convection 220 +5/-0 °C		Convection 235 +5/-0 °C
VPR 215-219 °C		VPR 235 +5/-0 °C
IR/Convection 220 +5/-0 °C		IR/Convection 235 +5/-0 °C

## Reliability test program

Test item	Method	Description
SOLDERABILITY	MIL-STD-883D-2003	245°C , 5 SEC
HOLT	MIL-STD-883D-1005.7	1000 Hrs Bias @ 125 °C
PCT	JESD-22-B, A102	168 Hrs, 100 % RH , 121°C
TST	MIL-STD-883D-1011.9	-65°C ~ 150°C, 200 Cycles
ESD	MIL-STD-883D-3015.7	VHBM > 2KV, VMM > 200V
Latch-Up	JESD 78	10ms , I <sub>tr</sub> > 100mA

## Carrier Tape & Reel Dimension



Application	A	B	C	J	T1	T2	W	P	E
SOP-8	330±1	62 ± 1.5	12.75 + 0.15	2 + 0.5	12.4 +0.2	2± 0.2	12 + 0.3 - 0.1	8± 0.1	1.75± 0.1
Application	F	D	D1	Po	P1	Ao	Bo	Ko	t
SOP-8	5.5 ± 0.1	1.55±0.1	1.55+ 0.25	4.0 ± 0.1	2.0 ± 0.1	6.4 ± 0.1	5.2± 0.1	2.1± 0.1	0.3±0.013

(mm)

## Cover Tape Dimensions

Application	Carrier Width	Cover Tape Width	Devices Per Reel
SOP- 8	12	9.3	2500

## Customer Service

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